



Product/Process Change Notice - PCN 11_0241 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

PCN Title: Conversion of Select LFCSP Package Outlines from Punch to Sawn and Transfer of Assembly Site to STATS ChipPAC Malaysia.

Publication Date: 09-Nov-2011

Effectivity Date: 07-Feb-2012 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release

Description Of Change

ADI has qualified and will be utilizing Assembly subcontractor Stats ChipPAC in Malaysia(SCM) for LFCSP products in 3x3, 4x4 and 5x5 packages. ADI has also qualified SCM's standard bill of materials in a Sawn singulated leadframe. Pin1 indicator will be laser marked as part of the change. See attachments for BOM changes, pin 1 marking comparison and package outline differences.

Reason For Change

Sawn LFCSP is ADI's technology direction for LFCSP. The use of ADI qualified SCM-Malaysia as an assembly site will ensure continued source of product supply. ADI's assembly subcontractors manufacture our products using Analog Devices specified manufacturing flows, process controls and monitors. This assures that our customers receive the same level of quality and reliability on products they receive from qualified ADI manufacturing locations.

Impact of the change (positive or negative) on fit, form, function & reliability

The devices function and reliability as specified by the product datasheet will be unaffected by these changes. The Foot Print Dimension will remain the same for both punch and sawn LFCSP package

Summary of Supporting Information

Qualification has been performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Report Summary.

Supporting Documents

Attachment 1: Type: Package Outline Drawing
ADI_PCN_11_0241_Rev_-_LFCSP POD.pdf

Attachment 2: Type: Qualification Report Summary
ADI_PCN_11_0241_Rev_-_LFCSP Qual Report.pdf

Attachment 3: Type: Detailed Change Description
ADI_PCN_11_0241_Rev_-_LFCSP BOM.pdf

Attachment 4: Type: Marking Comparison
ADI_PCN_11_0241_Rev_-_LFCSP Pin 1 Marking.pdf

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative

Americas: PCN_Americas@analog.com

Europe: PCN_Europe@analog.com

Japan: PCN_Japan@analog.com

Rest of Asia: PCN_ROA@analog.com

Appendix A - Affected ADI Models**Added Parts On This Revision - Product Family / Model Number (11)**

AD8324 / AD8324ACPZ	AD8324 / AD8324ACPZ-REEL7	AD9215 / AD9215BCPZ-105	AD9215 / AD9215BCPZ-65	AD9215 / AD9215BCPZ-80
ADF4107 / ADF4107BCPZ	ADF4107 / ADF4107BCPZ-REEL	ADF4107 / ADF4107BCPZ-REEL7	ADN2525 / ADN2525ACPZ-500R7	ADN2525 / ADN2525ACPZ-R2
ADN2525 / ADN2525ACPZ-REEL7				

Appendix B - Revision History

Rev	Publish Date	Rev Description
Rev. -	09-Nov-2011	Initial Release

Analog Devices, Inc.

DocId:1700 Parent DocId:1699 Layout Rev.6